

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	15	382/141-152.ccls. and (electronic near board circuit) with (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 12:53
L2	29	382/141-152.ccls. and (cream near2 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 12:57
L3	99	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 12:57
L4	40	(cream near solder) with (shape and (position\$4 locat\$4)) and inspection	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:00
L5	9	382/141-152.ccls. and (cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:00
L6	14	382/141-152.ccls. and group\$4 near4 (electron)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:00
L7	106	382/141-152.ccls. and slit near2 (light illuminat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:00
L8	9	382/141-152.ccls. and (cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:01

L9	14	382/141-152.ccls. and (group\$4) near2 (hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:01
L10	99	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:01
L11	0	"382"/\$.ccls. and (print \$4 and pattern and hole and image and judgement and result and inspection and element and group\$4 and identified and classified and display and connection and frame and solder and shape).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:03
L12	512	(FUKAGAWA near TAKAHIRO OTAKE near YUJI KATSUKI near TAKASHI MURAKAMI near MINORU YAMASAKI near KIMIYUKI).inv.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:05
L13	0	(FUKAGAWA near TAKAHIRO OTAKE near YUJI KATSUKI near TAKASHI MURAKAMI near MINORU YAMASAKI near KIMIYUKI).inv. and judgement and inspection and classifying	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:05
L14	0	(FUKAGAWA near TAKAHIRO OTAKE near YUJI KATSUKI near TAKASHI MURAKAMI near MINORU YAMASAKI near KIMIYUKI).inv. and judgement and inspection and classify \$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:05

L15	0	(FUKAGAWA near TAKAHIRO OTAKE near YUJI KATSUKI near TAKASHI MURAKAMI near MINORU YAMASAKI near KIMIYUKI).inv. and judgement and classify\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:05
L16	1	(FUKAGAWA near TAKAHIRO OTAKE near YUJI KATSUKI near TAKASHI MURAKAMI near MINORU YAMASAKI near KIMIYUKI).inv. and judgment and classify\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:06
L17	0	"382"/\$.ccls. and (print \$4 and pattern and hole and image and judgment and result and inspection and element and group\$4 and identified and classified and display and connection and frame and solder and shape).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/16 13:06
S1	2	("5134575").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/21 14:20
S2	2	("5134575").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 16:49
S3	100	382/150.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 20:14
S4	7	382/150.ccls. and (cream near2 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 20:14

S5	7	382/150.ccls. and (cream near2 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 17:39
S6	21	382/141-152.ccls. and (cream near2 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 17:39
S7	14	382/141-152.ccls. and (cream near2 solder) not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/12 03:59
S8	5904	(cream near solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 18:15
S9	87	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 18:16
S10	35	(cream near solder) with (shape and (position\$4 locat\$4)) and inspection	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 18:17
S11	21	382/141-152.ccls. and (cream near2 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/23 23:11
S12	88	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/23 23:12
S13	4338	382/141-152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/12 10:14
S14	191	382/141-152.ccls. and group\$4 near4 (hole pattern solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/12 12:36

S15	13	382/141-152.ccls. and group\$4 near4 (electron)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/12 12:37
S16	8	382/141-152.ccls. and group\$4 near4 (electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/12 12:37
S17	0	"10626140".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 13:45
S18	3	"6729532".pn..pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/20 13:45
S19	3	"6729532".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/21 14:20
S20	4	("20020180962" "5656507" "6170155" "6317513").PN. OR ("6729532").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/12/21 14:21
S21	204	382/141-152.ccls. and group\$4 near4 (hole pattern solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/21 14:23
S22	90	382/141-152.ccls. and slit near2 (light illuminat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/12/21 15:15
S23	8	382/141-152.ccls. and group\$4 near4 (electrode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/25 14:12
S24	4	("5991435" "4978224").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/25 14:15

S25	392	382/141-152.ccls. and (select\$4 choos\$4) near3 (group\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 02:01
S26	2	"20040146195".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 02:01
S27	2	"20040146195".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 13:13
S28	3	"6729532".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 13:29
S29	4	("5991435" "4978224"). pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 13:30
S30	98	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 13:34
S31	9	382/141-152.ccls. and (cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/20 14:42
S32	4	("5991435" "4978224"). pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/08 15:14
S33	98	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 01:16
S34	9	382/141-152.ccls. and (cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 01:16

S35	232	382/141-152.ccls. and (group\$4) near4 (hole pattern solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 01:17
S36	14	382/141-152.ccls. and (group\$4) near2 (hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 01:18
S37	4	("20020180962" "5656507" "6170155" "6317513").PN. OR ("6729532").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/06/09 13:32
S38	136	382/141-152.ccls. and group\$4 near2 (hole pattern solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 14:03
S39	21	382/141-152.ccls. and group\$4 near2 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 14:03
S40	117	382/141-152.ccls. and group\$4 near2 (pattern)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 14:16
S41	98	(cream near solder) with (shape and (position\$4 locat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 20:52
S42	492667	(arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole pattern electr\$3 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 21:05
S43	676	382/141-152.ccls. and (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole pattern electr\$3 solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 21:06
S44	100	382/141-152.ccls. and (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/09 21:06

S45	5200	(electronic near board circuit) with (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/10 16:09
S46	0	382/141-152.ccls and (electronic near board circuit) with (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/10 16:10
S47	15	382/141-152.ccls. and (electronic near board circuit) with (arrang\$4 cluster\$4 gather\$4 group\$4) near3 (hole solder)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/10 16:10

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	0	"382"/\$.ccls. and (print\$4 and pattern and hole and image and judgment and result and inspection and element and group\$4 and identified and classified and display and connection and frame and solder and shape).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2009/09/16 13:06

9/16/2009 1:18:27 PM**C:\Documents and Settings\aliew\My Documents\EAST\Workspaces\10626140.wsp**